

MB1M~MB10M

Rev.D May.-2017

描述 / Descriptions

0.8A 直插玻璃钝化整流桥，MBM 封装。

0.8A DIP Glass Passivated Bridge Rectifier, MBM package.

特征 / Features

玻璃钝化芯片，反向电压：100V~1000V，正向电流：0.8A，浪涌电流大。

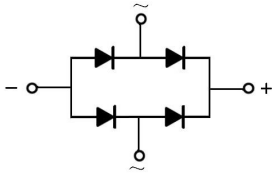
Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current: 0.8 A, High Surge Current Capability.

用途 / Applications

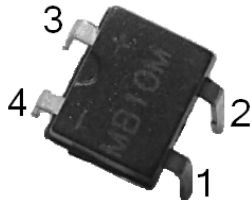
一般用途。

General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 50^\circ\text{C}$	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Typical Junction Capacitance ^(Note1)	C_j	13						pF
Typical Thermal Resistance ^(Note2)	$R_{\theta JA}$	95						°C/W
Typical Thermal Resistance ^(Note2)	$R_{\theta JL}$	30						°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150						°C

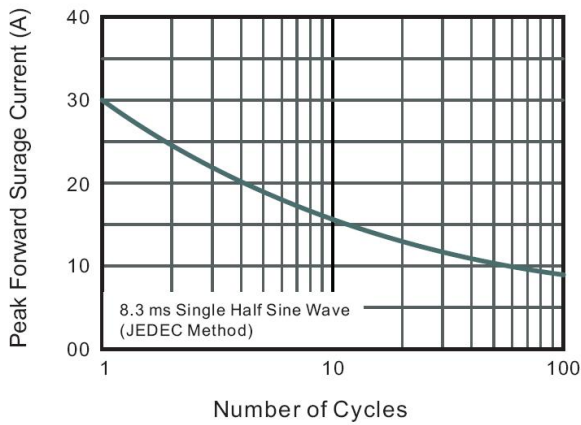
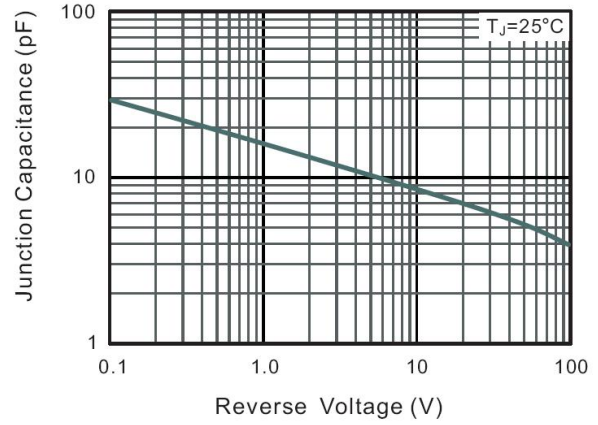
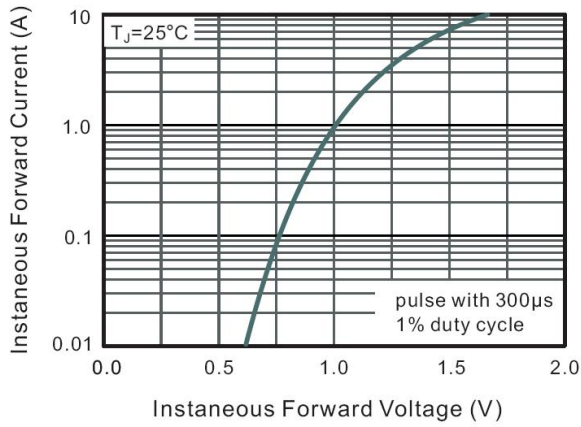
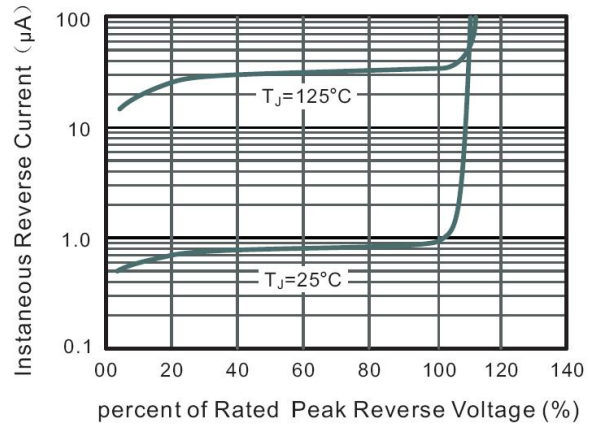
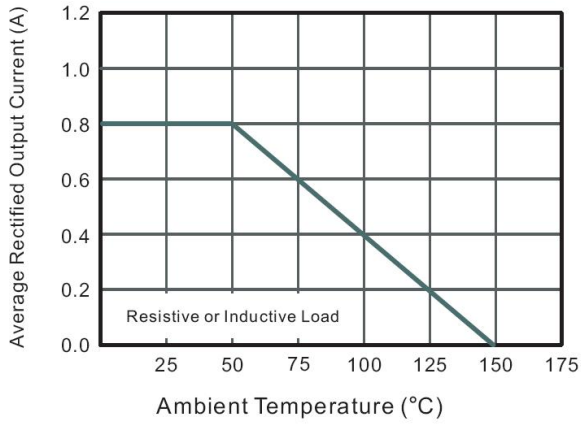
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad..

电性能参数 / Electrical Characteristics(Ta=25°C)

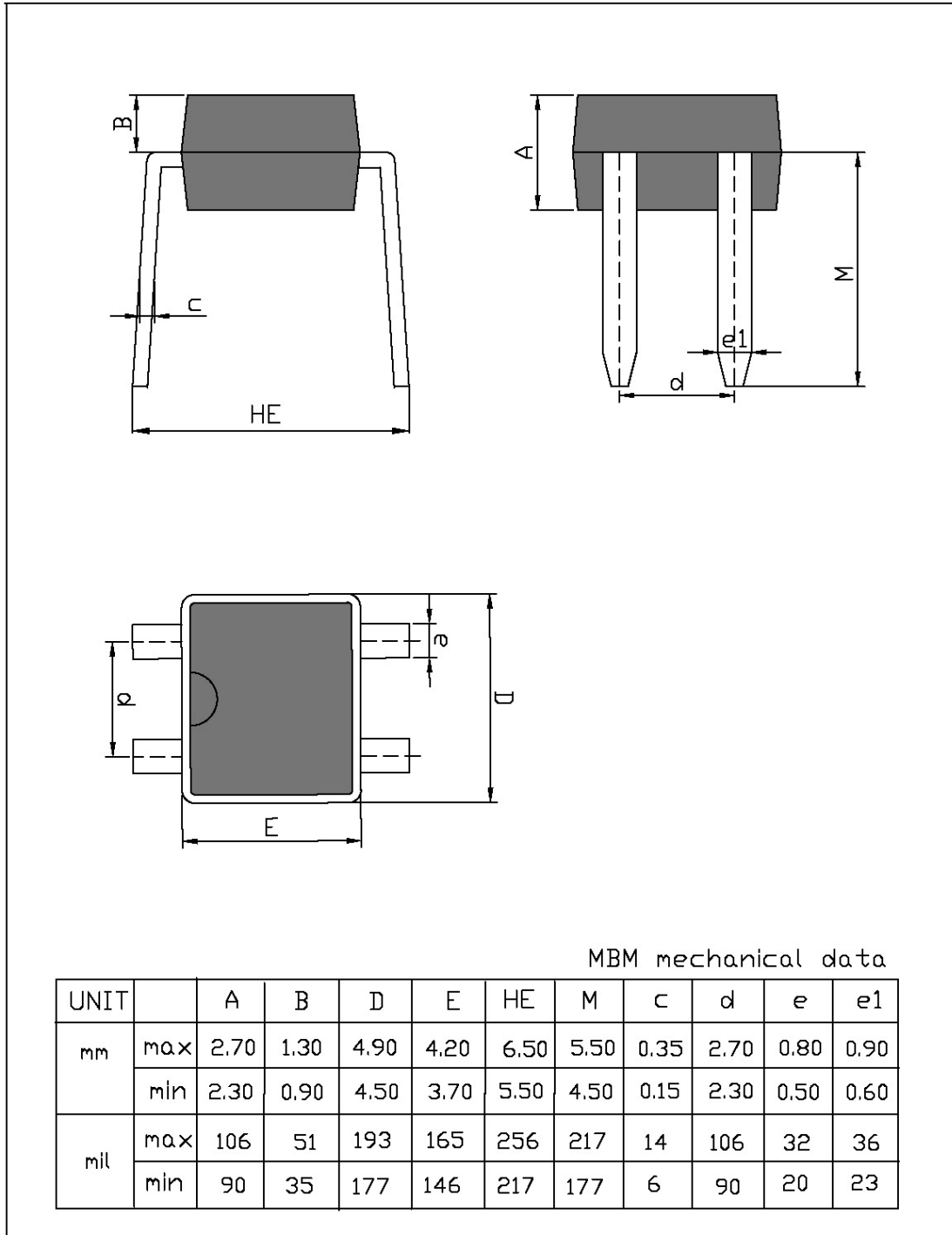
参数 Parameter	符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	$I_F=0.4\text{A}$	1.0	V
		$I_F=0.8\text{A}$	1.1	
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	5.0	μA
		$T_a=125^\circ\text{C}$	40	

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

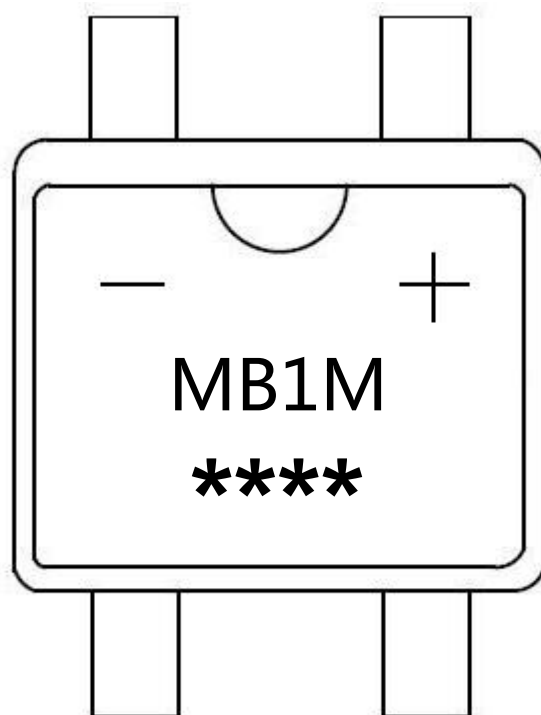
MBM



Marking

Type number	Marking code
MB1M	MB1M
MB2M	MB2M
MB4M	MB4M
MB6M	MB6M
MB8M	MB8M
MB10M	MB10M

印章说明 / Marking Instructions



说明：

MB1M：为型号代码

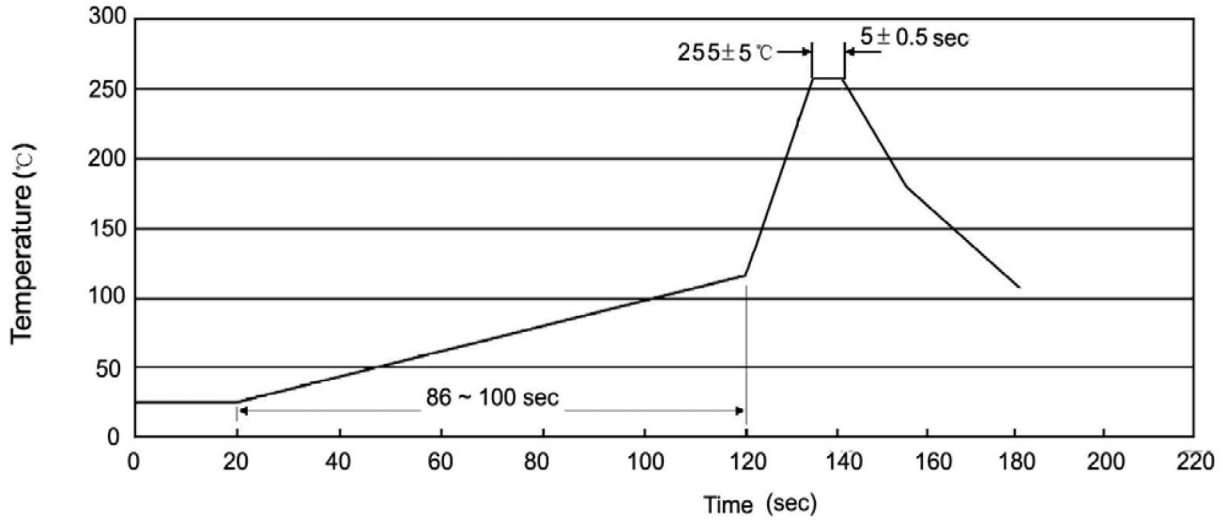
****：为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

MB1M：Product Type Code

****：Lot No. Code，The 1st * means:YM Code，The last 3 * means:little Lot No Code

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C 时间：10±1 sec. Temp.:270±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
MBM	100	50	5000	4	20000			

使用说明 / Notices